



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C	
001/	$38m\Omega$ @ V _{GS} = -4.5V	-5.4A	
-20V	56mΩ @ V _{GS} = -2.5V	-4.4A	

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative.

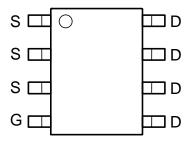
https://www.diodes.com/quality/product-definitions/

Mechanical Data

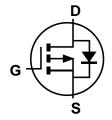
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.072g (Approximate)



Top View



Pin-Out Top View



Equivalent Circuit

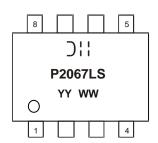
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2067LSS-13	SO-8	2500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



);; = Manufacturer's Marking
P2067LS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY= Year (ex: 20 = 2020)
WW = Week (01 to 53)



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	-20	V		
Gate-Source Voltage	Vgss	±8	V		
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Steady State	T _A = +25°C T _A = +70°C	ID	-5.4 -3.2	А
Continuous Drain Current (Note 7) V _{GS} = -4.5V	Steady State	T _C = +25°C T _C = +70°C	lD	-12.9 -10.4	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	IDM	-30	Α		
Continuous Source-Drain Diode Current (Note 6)			Is	-1.4	А

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	P _D	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	RθJA	104	°C/W
Total Power Dissipation (Note 6)	T _A = +25°C	P _D	1.67	W
Thermal Resistance, Junction to Ambient (Note 6) Steady State		$R_{\theta JA}$	75	°C/W
Thermal Resistance, Junction to Case (Note 7) Steady State		Rejc	14	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C	

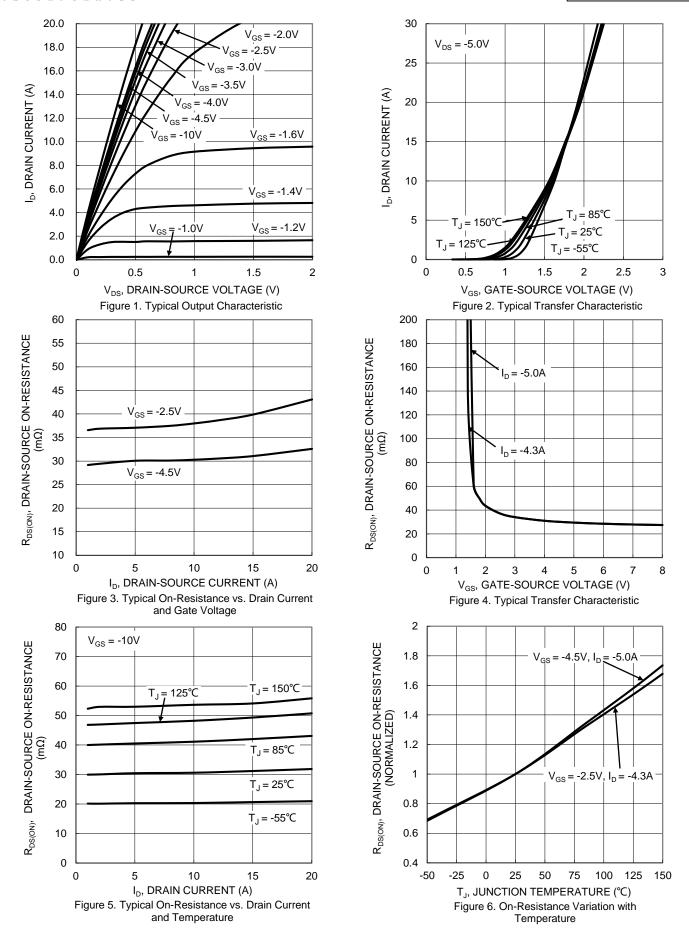
Electrical Characteristics (TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	-100	nA	V _{DS} = -16V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	-0.5	_	-1.5	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	
Static Drain-Source On-Resistance	Dagger	_	31	38	mΩ	V _{GS} = -4.5V, I _D = -5A	
Static Dialit-Source Off-Nesistance	RDS(ON)	_	37	56		Vgs = -2.5V, ID = -4.3A	
Diode Forward Voltage	VsD	-0.5	-0.7	-1.2	V	V _G S = 0V, I _S = -2.1A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	1575	_		V _{DS} = -10V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	124	_	pF		
Reverse Transfer Capacitance	Crss	_	89	_			
Gate Resistance	R_g	_	10	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	27.9	_			
Total Gate Charge (V _{GS} = -8V)	Qg	_	15.5	_	nC	10// 154	
Gate-Source Charge	Qgs	_	1.6	_	IIC	V _{DS} = -10V, I _D = -4.5A	
Gate-Drain Charge	Q_{gd}	_	3.4	_			
Turn-On Delay Time	td(ON)	_	5.2	_			
Turn-On Rise Time	t _R	_	12.2	_		$V_{DD} = -5V$, $R_L = 6\Omega$	
Turn-Off Delay Time	t _{D(OFF)}	_	103	_	ns	$V_{GS} = -4.5V, R_g = 6\Omega, I_D = -1A$	
Turn-Off Fall Time	t _F	_	30.7	_			
Body Diode Reverse Recovery Time	trr	_	13	_	ns	I _F = -8.9A, di/dt = -100A/μs	
Body Diode Reverse Recovery Charge	Qrr	_	6.3	_	nC	I _F = -8.9A, di/dt = -100A/μs	

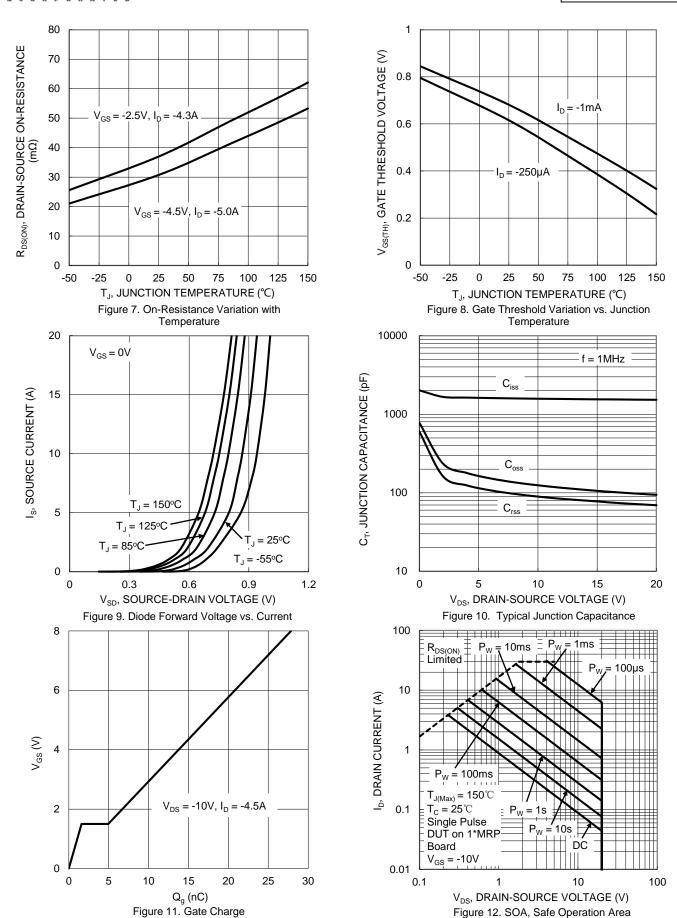
- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout, single sided.
- Device mounted on FR-4 PCB, with minimum recommended pad layout, single sided.
 Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 Thermal resistance from junction to soldering point (on the exposed drain pad).
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.

DMP2067LSS Document number: DS41378 Rev. 3 - 2











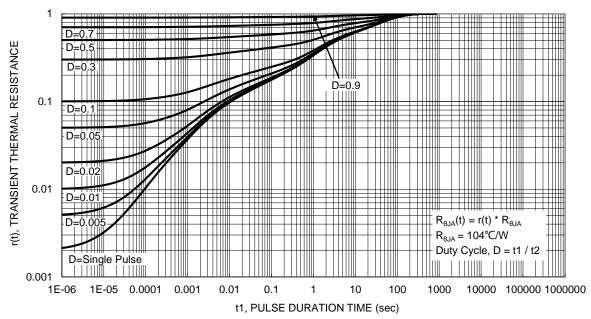


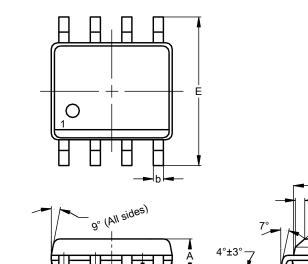
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



	SO-8				
Dim	Min	Max	Тур		
Α	1.40	1.50	1.45		
A1	0.10	0.20	0.15		
b	0.30	0.50	0.40		
С	0.15	0.25	0.20		
D	4.85	4.95	4.90		
Е	5.90	6.10	6.00		
E1	3.80	3.90	3.85		
E0	3.85	3.95	3.90		
е	-		1.27		
h			0.35		
L	0.62	0.82	0.72		
ø	0.60	0.70	0.65		
All Dimensions in mm					

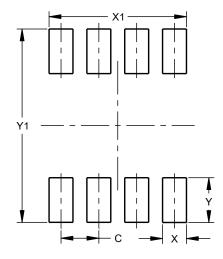
Suggested Pad Layout

80.1

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8

Gauge Plane Seating Plane



Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Υ	1.505
Y1	6.50



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